3.3 V ECL 4-Input OR/NOR

Description

The MC100LVEL01 is a 4-input OR/NOR gate. The device is functionally equivalent to the EL01 device and works from a 3.3 V supply. With AC performance similar to the EL01 device, the LVEL01 is ideal for low voltage applications which require the ultimate in AC performance.

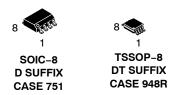
Features

- 370 ps Propagation Delay
- High Bandwidth Output Transitions
- ESD Protection:
 - ♦ > 2 kV Human Body Model
 - ♦ > 200 V Machine Model
- The 100 Series Contains Temperature Compensation
- PECL Mode Operating Range: $V_{CC} = 3.0 \text{ V}$ to 3.8 V with $V_{EE} = 0 \text{ V}$
- NECL Mode Operating Range: $V_{CC} = 0 V$ with $V_{EE} = -3.0 V$ to -3.8 V
- Internal Input Pulldown Resistors
- Q Output will Default LOW with All Inputs Open or at V_{EE}
- Meets or Exceeds JEDEC Spec EIA/JESD78 IC Latchup Test
- Moisture Sensitivity
 - ◆ Level 1 for SOIC-8
 - Level 3 for TSSOP-8
 - For Additional Information, see Application Note AND8003/D
- Flammability Rating: UL 94 V–0 @ 0.125 in,
 - Oxygen Index 28 to 34
- Transistor Count = 83 Devices
- These Devices are Pb-Free and are RoHS Compliant

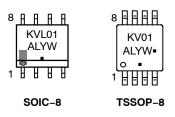


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MARKING DIAGRAMS*



A = Assembly Location

- L = Wafer Lot
- Y = Year
- W = Work Week
- \overline{M} = Date Code
- = Pb-Free Package

(Note: Microdot may be in either location) *For additional marking information, refer to Application Note <u>AND8002/D</u>.

ORDERING INFORMATION

Device	Package	Shipping†
MC100LVEL01DG	SOIC–8 (Pb-Free)	98 Units / Tube
MC100LVEL01DR2G	SOIC-8 (Pb-Free)	2500 Tape & Reel
MC100LVEL01DTG	TSSOP–8 (Pb-Free)	100 Units / Tube

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, <u>BRD8011/D</u>.

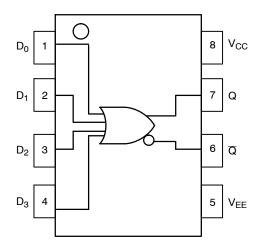


Figure 1. Logic Diagram and Pinout Assignment

Table 2. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Units
V _{CC}	PECL Mode Power Supply	V _{EE} = 0 V		8 to 0	V
V_{EE}	NECL Mode Power Supply	V _{CC} = 0 V		–8 to 0	V
VI	$ \begin{array}{llllllllllllllllllllllllllllllllllll$		6 to 0 6 to 0	V	
I _{out}	Output Current	Continuous Surge		50 100	mA
T _A	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	ent) 0 lfpm SOIC-8 500 lfpm SOIC-8		190 130	°C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	SOIC-8	41 to 44 ±5%	°C/W
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	TSSOP-8 TSSOP-8	185 140	°C/W
θJC	Thermal Resistance (Junction-to-Case)	Standard Board	TSSOP-8	41 to 44 ±5%	°C/W
T _{sol}	Wave Solder (Pb-Free)	< 2 to 3 sec @ 260°C		265	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 1. PIN DESCRIPTION

PIN	FUNCTION
D0-D3	ECL Data Inputs
Q, Q	ECL Data Outputs
V _{CC}	Positive Supply
V _{EE}	Negative Supply

Table 3. LVPECL DC CHARACTERISTICS (V_{CC} = 3.3 V; V_{EE} = 0 V (Note 1))

			-40°C		25°C		85°C				
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current		15	20		15	20		17	22	mA
V _{OH}	Output HIGH Voltage (Note 2)	2215	2295	2420	2275	2345	2420	2275	2345	2420	mV
V _{OL}	Output LOW Voltage (Note 2)	1470	1605	1745	1490	1595	1680	1490	1595	1680	mV
V _{IH}	Input HIGH Voltage	2135		2420	2135		2420	2135		2420	mV
V_{IL}	Input LOW Voltage	1490		1825	1490		1825	1490		1825	mV
I _{IH}	Input HIGH Current			150			150			150	μA
۱ _{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

1. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary ±0.3 V.

2. Outputs are terminated through a 50 Ω resistor to V_{CC} – 2.0 V.

Table 4. LVNECL DC CHARACTERISTICS (V_{CC} = 0 V; V_{EE} = -3.3 V (Note 1))

			-40°C		25°C		85°C				
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current		15	20		15	20		17	22	mA
V _{OH}	Output HIGH Voltage (Note 2)	-1085	-1005	-880	-1025	-955	-880	-1025	-955	-880	mV
V _{OL}	Output LOW Voltage (Note 2)	-1830	-1695	-1555	-1810	-1705	-1620	-1810	-1705	-1620	mV
V _{IH}	Input HIGH Voltage	-1165		-880	-1165		-880	-1165		-880	mV
V _{IL}	Input LOW Voltage	-1810		-1475	-1810		-1475	-1810		-1475	mV
I _{IH}	Input HIGH Current			150			150			150	μA
Ι _{ΙL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

1. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary ± 0.3 V.

2. Outputs are terminated through a 50 Ω resistor to V_{CC}-2 volts.

Table 5. AC CHARACTERISTICS ($V_{CC} = 3.3 \text{ V}$; $V_{EE} = 0 \text{ V}$ or $V_{CC} = 0 \text{ V}$; $V_{EE} = -3.3 \text{ V}$ (Note 1))

		-40°C		25°C			85°C				
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f _{max}	Maximum Toggle Frequency		TBD			TBD			TBD		GHz
t _{PLH} t _{PHL}	Propagation Delay to Output	210	310	510	270	370	470	290	390	490	ps
t _{skew}	Within Device Skew		40	100		40	100		40	100	ps
t JITTER	Cycle-to-Cycle Jitter		TBD			TBD			TBD		ps
t _r t _f	Output Rise/Fall Times Q (20%-80%)	120	225	320	120	225	320	120	225	320	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

1. V_{EE} can vary ±0.3 V.

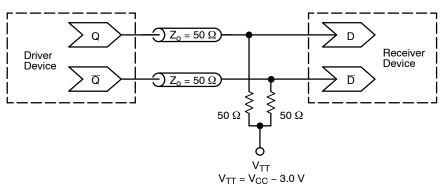
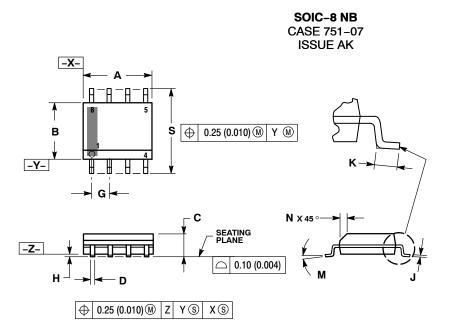


Figure 2. Typical Termination for Output Driver and Device Evaluation (See Application Note <u>AND8020/D</u> – Termination of ECL Logic Devices)

Resource Reference of Application Notes

AN1405/D	-	ECL Clock Distribution Techniques
AN1406/D	-	Designing with PECL (ECL at +5.0 V)
AN1503/D	-	ECLinPS [™] I/O SPiCE Modeling Kit
AN1504/D	-	Metastability and the ECLinPS Family
AN1568/D	-	Interfacing Between LVDS and ECL
AN1672/D	-	The ECL Translator Guide
AND8001/D	-	Odd Number Counters Design
AND8002/D	-	Marking and Date Codes
AND8020/D	-	Termination of ECL Logic Devices
AND8066/D	-	Interfacing with ECLinPS
AND8090/D	-	AC Characteristics of ECL Devices

PACKAGE DIMENSIONS

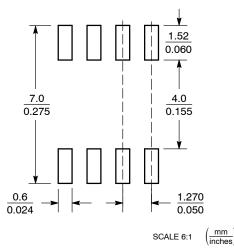


NOTES: 1. DIMENSIONING AND TOLERANCING PER

- ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER. 2.
- DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION. З.
- 4.
- MOLD PROTRUSION. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07. 5.
- 6.

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	4.80	5.00	0.189	0.197	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.053	0.069	
D	0.33	0.51	0.013	0.020	
G	1.27	7 BSC	0.050 BSC		
н	0.10	0.25	0.004	0.010	
J	0.19	0.25	0.007	0.010	
К	0.40	1.27	0.016	0.050	
М	0 °	8 °	0 °	8 °	
Ν	0.25	0.50	0.010	0.020	
S	5.80	6.20	0.228	0.244	

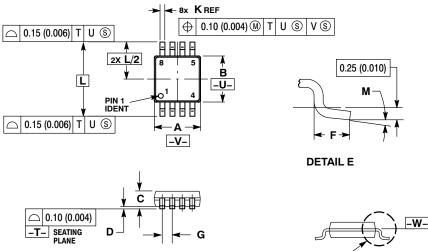
SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS





DETAIL E-

NOTES:	

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
- CONTROLLING DIMENSION: MILLIMETER.
 DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15
- (0.006) PER SIDE. 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE
- 5. TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY. 6. DIMENSION A AND B ARE TO BE DETERMINED
- DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIN	IETERS	INCHES				
DIM	MIN	MAX	MIN	MAX			
Α	2.90	3.10	0.114	0.122			
В	2.90	3.10	0.114	0.122			
C	0.80	1.10	0.031	0.043			
D	0.05	0.15	0.002	0.006			
F	0.40	0.70	0.016	0.028			
G	0.65	BSC	0.026	BSC			
K	0.25	0.40	0.010	0.016			
L	4.90	4.90 BSC		BSC			
M	0°	6 °	0°	6 °			

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